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(19) **United States**(12) **Patent Application Publication** (10) **Pub. No.: US 2024/0179836 A1**
YOSHIDA (43) **Pub. Date: May 30, 2024**(54) **FLEXIBLE BOARD, LIQUID JET HEAD, AND
LIQUID JET RECORDING DEVICE**(57) **ABSTRACT**(71) Applicant: **SHI Printek Inc.**, Chiba-shi (JP)(72) Inventor: **Kensuke YOSHIDA**, Chiba-shi (JP)(21) Appl. No.: **18/387,184**(22) Filed: **Nov. 6, 2023**(30) **Foreign Application Priority Data**

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The flexible board according to an embodiment of the present disclosure includes a first wiring layer and a second wiring layer opposed to each other along a direction perpendicular to a board surface of the flexible board, at least one drive device which is arranged on the first wiring layer, and which is configured to generate a drive signal, an individual wiring region which is arranged in the first wiring layer, and which includes a plurality of individual wiring lines, a common wiring region which is arranged in the second wiring layer, and which includes at least one common wiring line, a pressure-bonding electrode part which is arranged closed to the jet section side than the individual wiring region and the common wiring region in the board surface, and which includes a plurality of pressure-bonding electrodes electrically coupled individually to the plurality of individual wiring lines and the at least one common wiring line, and an overlap region in which at least a part of the individual wiring region and at least a part of the common wiring region overlap each other in the board surface.

